



BYC5-600P

Hyperfast power diode

24 December 2014

Product data sheet

1. General description

Hyperfast power diode in a SOD59 package.

2. Features and benefits

- Low leakage current
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET or IGBT

3. Applications

- Half-bridge/full-bridge switched-mode power supplies
- Continuous Current Mode (CCM) Power Factor Correction (PFC)

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_{mb} \leq 133$ °C; square-wave pulse; Fig. 1 ; Fig. 2 ; Fig. 3	-	-	5	A
Static characteristics						
V_F	forward voltage	$I_F = 5$ A; $T_j = 25$ °C; Fig. 6	-	2.5	3.3	V
		$I_F = 5$ A; $T_j = 150$ °C; Fig. 6	-	1.4	2.1	V
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $dI_F/dt = 200$ A/ μ s; $T_j = 25$ °C; Fig. 7	-	11	-	ns

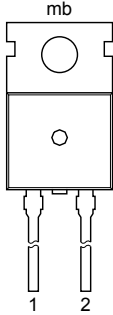
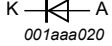


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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220AC (SOD59)</p>	
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYC5-600P	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

7. Marking

Table 4. Marking codes

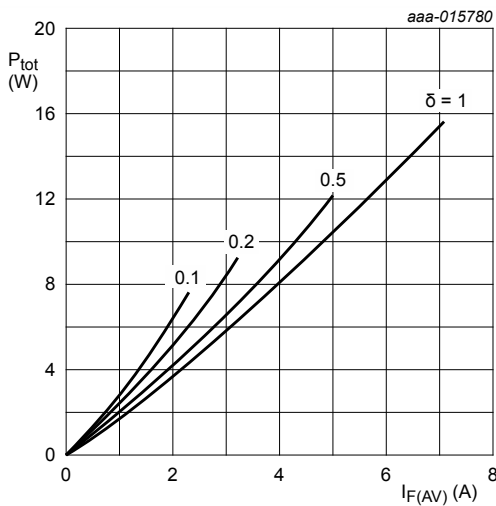
Type number	Marking code
BYC5-600P	BYC5-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

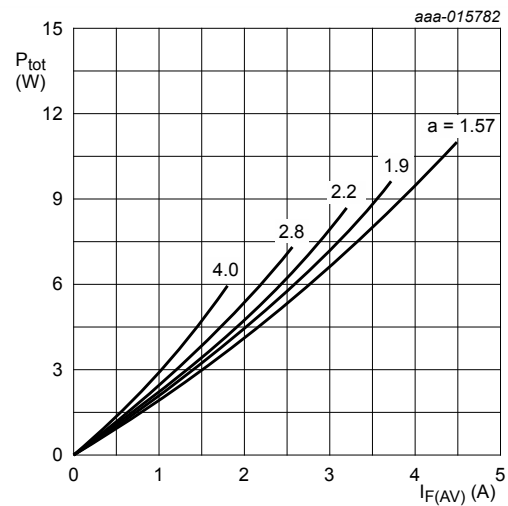
Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	600	V
V_{RWM}	crest working reverse voltage		-	600	V
V_R	reverse voltage	DC	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_{mb} \leq 133\text{ }^\circ\text{C}$; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	-	5	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 133\text{ }^\circ\text{C}$; square-wave pulse	-	10	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse; Fig. 4	-	60	A
		$t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse; Fig. 4	-	65	A
T_{stg}	storage temperature		-65	175	$^\circ\text{C}$
T_j	junction temperature		-	175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.801\text{ V}; R_s = 0.062\text{ }\Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 1.801\text{ V}; R_s = 0.062\text{ }\Omega$$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

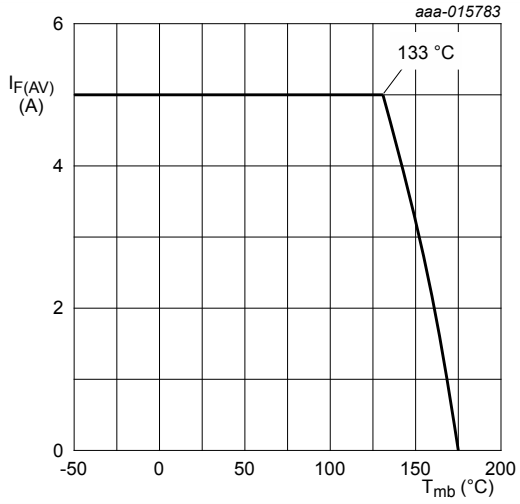


Fig. 3. Forward current as a function of mounting base temperature; maximum values

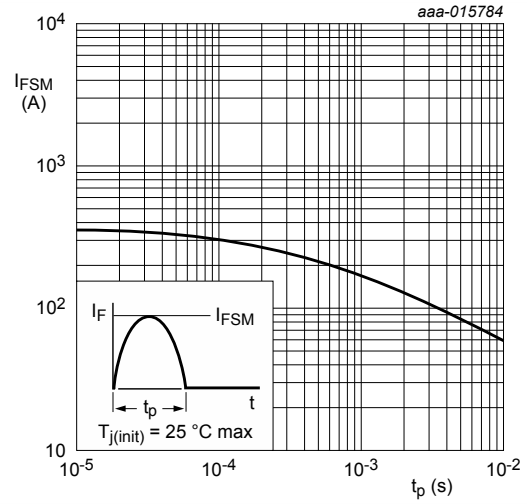


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; Fig. 5	-	-	3.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

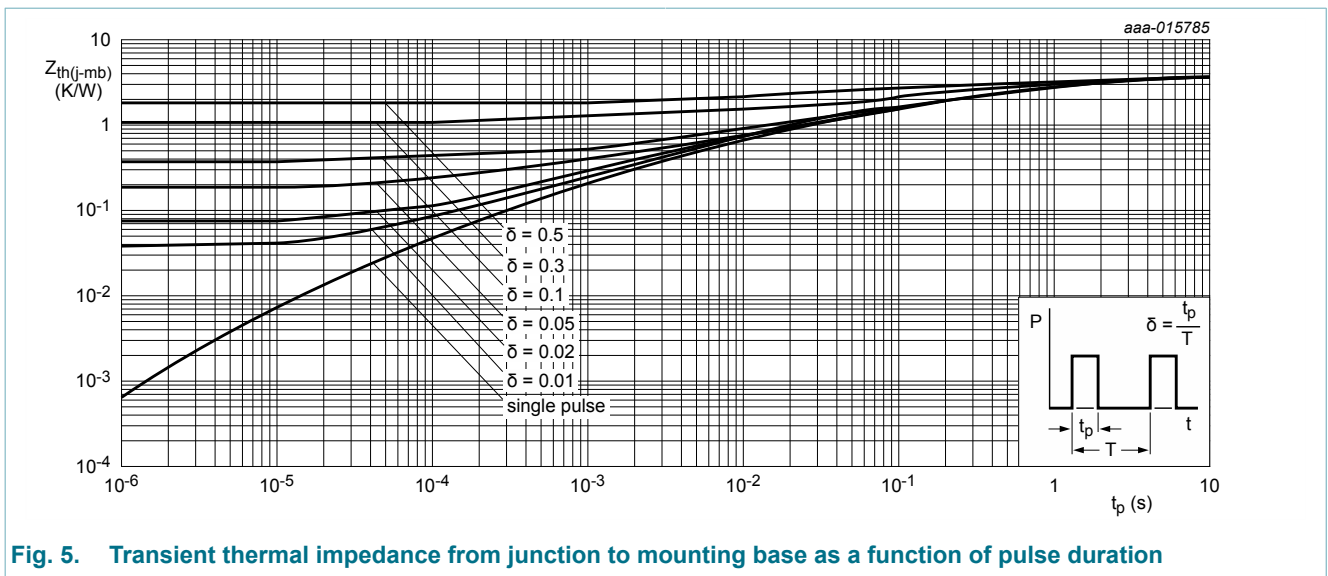
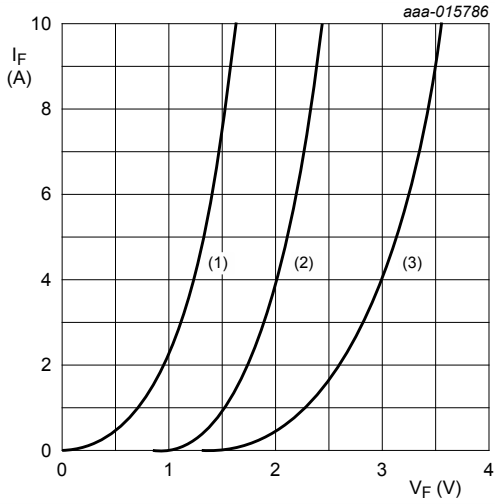


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _F	forward voltage	I _F = 5 A; T _j = 25 °C; Fig. 6	-	2.5	3.3	V
		I _F = 5 A; T _j = 150 °C; Fig. 6	-	1.4	2.1	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C	-	-	10	μA
		V _R = 600 V; T _j = 150 °C	-	-	0.6	mA
Dynamic characteristics						
Q _r	recovered charge	I _F = 5 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7	-	19	-	nC
		I _F = 5 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7	-	45	-	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7	-	11	-	ns
		I _F = 5 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7	-	23	-	ns
		I _F = 5 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7	-	28	-	ns
		I _F = 5 A; V _R = 400 V; dI _F /dt = 500 A/μs; T _j = 25 °C; Fig. 7	-	13	25	ns
I _{RM}	peak reverse recovery current	I _F = 5 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7	-	1.7	-	A
		I _F = 5 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7	-	3.2	-	A



$V_o = 1.801 \text{ V}; R_s = 0.062 \text{ } \Omega$

- (1) $T_j = 150 \text{ } ^\circ\text{C}$; typical values
- (2) $T_j = 150 \text{ } ^\circ\text{C}$; maximum values
- (3) $T_j = 25 \text{ } ^\circ\text{C}$; maximum values

Fig. 6. Forward current as a function of forward voltage

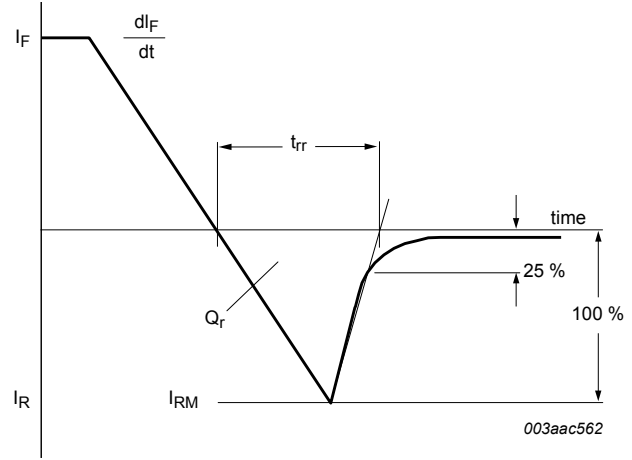
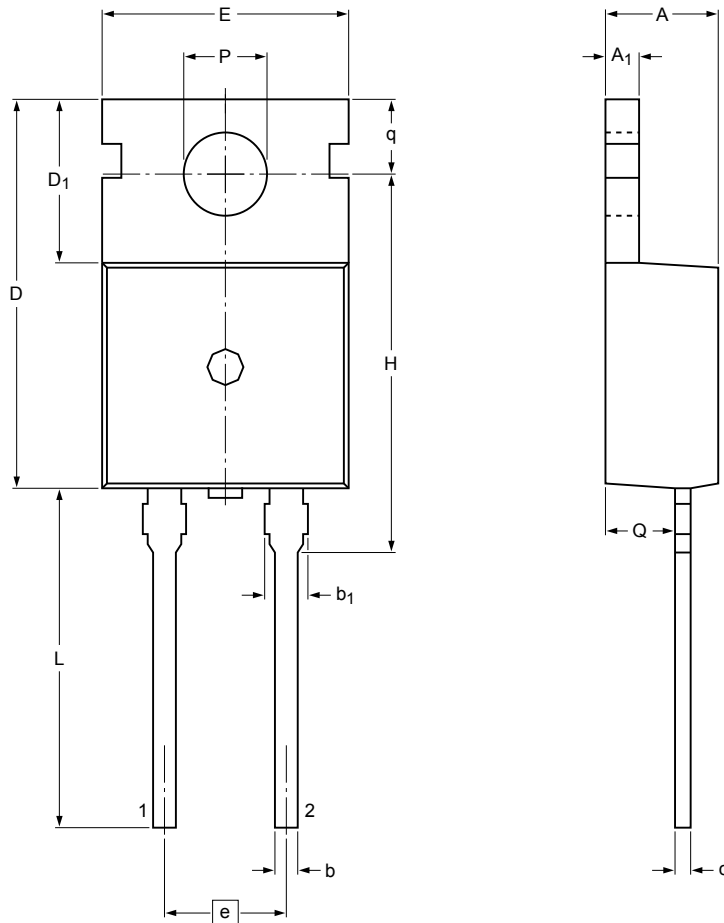


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC SOD59



Dimensions

Unit	A	A ₁	b	b ₁ ⁽¹⁾	c	D	D ₁	E	e	H	L	P	Q	q
max	4.7	1.40	0.95	1.7	0.65	15.8	6.8	10.30	5.08	16.25	15.0	3.80	2.6	2.9
nom									(REF)					
min	4.3	1.15	0.70	1.3	0.45	15.6	6.4	9.65		15.70	12.5	3.65	2.2	2.7

Note

1. Protruded dambar are included in the dimension.

sod059_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD59	2-lead TO-220AC				09-08-25 12-11-27

Fig. 8. Package outline TO-220AC (SOD59)

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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